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Thermal Metamaterials and Thermal Functional Devices

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Message from the Guest Editors

Dear Colleagues,

The purpose of this Special Issue is to highlight recent advances in thermal metamaterials and metadevices with dramatically engineered thermal properties and functionalities. Examples include heat flow manipulation, thermal management, engineered thermal emission, symmetry and topological properties in heat transfer systems, enhanced phonon transport in low-dimensional systems or across heterointerfaces, emerging macro/microscale thermal functionalities, practical applications of thermal metamaterials, etc.

This Special Issue covers all aspects of thermal metamaterials and thermal functional devices, with an emphasis on understanding the role of ordered functional units, basic physics that determine metamaterials' functionality, novel design tools and manufacturing methods, numerical modelling, and experimental methods.

Prof. Dr. Run Hu
Prof. Dr. Ying Li
Guest Editors



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Special Issue



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Message from the Editor-in-Chief

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